

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUC100N10S5L040	**Issued**	11. December 2019
MA#	MA005346576		
Package	PG-TDSON-8-34	**Weight***	113.59 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.175	1.91	1.91	19145	19145
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		140	
	non noble metal	iron	7439-89-6	0.053	0.05		466	
	non noble metal	copper	7440-50-8	52.842	46.54	46.60	465181	465787
wire	noble metal	gold	7440-57-5	0.042	0.04	0.04	370	370
encapsulation	organic material	carbon black	1333-86-4	0.073	0.06		644	
	plastics	epoxy resin	-	5.778	5.09		50868	
	inorganic material	silicondioxide	60676-86-0	30.720	27.04	32.19	270436	321948
leadfinish	non noble metal	tin	7440-31-5	1.574	1.39	1.39	13855	13855
plating	noble metal	silver	7440-22-4	0.209	0.18	0.18	1842	1842
solder	non noble metal	tin	7440-31-5	0.046	0.04		407	
	noble metal	silver	7440-22-4	0.058	0.05		509	
	non noble metal	lead	7439-92-1	2.210	1.95	2.04	19453	20369
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		44	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	non noble metal	copper	7440-50-8	16.828	14.81	14.82	148138	148330
clip plating	noble metal	silver	7440-22-4	0.639	0.56	0.56	5625	5625
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2725	2729
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com